TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

## 2SK2598

# Chopper Regulator, DC-DC Converter and Motor Drive Applications

 $\begin{array}{ll} \bullet & Low\ drain-source\ ON\ resistance & :\ RDS\ (ON) = 0.18\ \Omega\ (typ.) \\ \bullet & High\ forward\ transfer\ admittance & :\ |\ Y_{fs}| = 13\ S\ (typ.) \\ \bullet & Low\ leakage\ current & :\ IDSS = 100\ \mu A\ (max)\ (VDS = 250\ V) \\ \bullet & Enhancement\ mode & :\ V_{th} = 1.5 {\sim} 3.5\ V\ (VDS = 10\ V,\ ID = 1\ mA) \\ \end{array}$ 

#### Absolute Maximum Ratings (Ta = 25°C)

Characteri	stics	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	250	V	
Drain-gate voltage (R	<sub>GS</sub> = 20 kΩ)	$V_{DGR}$	250	V	
Gate-source voltage		V <sub>GSS</sub>	±20	V	
Drain current	DC (Note 1)	I <sub>D</sub>	13	А	
	Pulse (Note 1)	$I_{DP}$	52		
Drain power dissipatio	n (Tc = 25°C)	$P_{D}$	60	W	
Single pulse avalanche energy (Note 2)		E <sub>AS</sub>	148	mJ	
Avalanche current		I <sub>AR</sub>	13	А	
Repetitive avalanche energy (Note 3)		E <sub>AR</sub>	6	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	2.08	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	83.3	°C/W

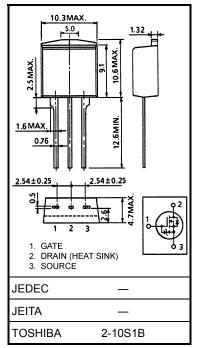
Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2:  $V_{DD} = 50 \text{ V}$ ,  $T_{ch} = 25^{\circ}\text{C}$  (initial), L = 1.48 mH,  $R_G = 25 \Omega$ ,  $I_{AR} = 13 \text{ A}$ 

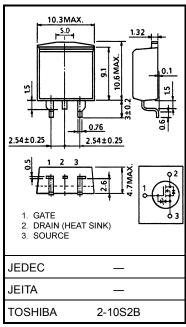
Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.

Unit: mm



Weight: 1.5 g (typ.)



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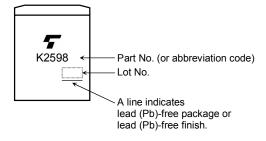
## **Electrical Characteristics (Ta = 25°C)**

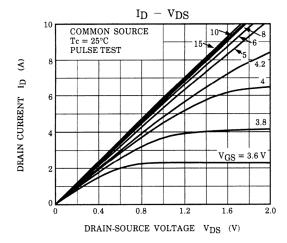
Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V	_	_	±10	μA
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 250 V, V <sub>GS</sub> = 0 V	_	_	100	μΑ
Drain-source br	eakdown voltage	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	200	_	_	V
Gate threshold v	voltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	1.5	_	3.5	V
Drain-source O	N resistance	R <sub>DS (ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 6.5 A	_	0.18	0.25	Ω
Forward transfe	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 6.5 A	6	13	_	S
Input capacitano	ce	C <sub>iss</sub>		-	1800	-	
Reverse transfe	r capacitance	C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	130	_	pF
Output capacita	nce	Coss			500	_	
Tul Switching time Fal	Rise time	t <sub>r</sub>	$V_{GS} = 0 \text{ V}$ $V_{GS} = 0 \text{ V}$ $V_{DD} = 130 \text{ V}$	_	15	_	
	Turn-on time	t <sub>on</sub>		_	25	_	nc
	Fall time	t <sub>f</sub>		_	10	_	- ns
	Turn-off time	t <sub>off</sub>	Duty $\leq 1\%$ , $t_{\rm w} = 10 \mu \rm s$	_	70	_	
Total gate charge (Gate-source plus gate-drain)		Qg		_	40	_	
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \approx 200 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 13 \text{ A}$	_	25	_	nC
Gate-drain ("miller") charge		Q <sub>gd</sub>	]		15	_	

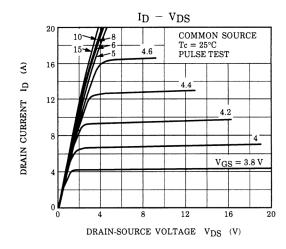
## Source-Drain Ratings and Characteristics (Ta = 25°C)

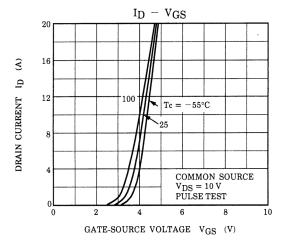
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_		_	13	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	-		_	52	Α
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 13 A, V <sub>GS</sub> = 0 V		_	-2.0	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 13 A, V <sub>GS</sub> = 0 V	1	260	_	ns
Reverse recovery charge	Qrr	dl <sub>DR</sub> / dt = 100 A / μs	_	0.3	_	μC

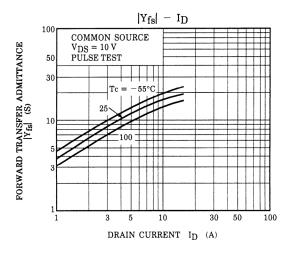
## Marking

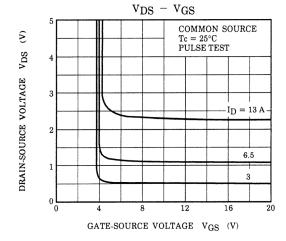


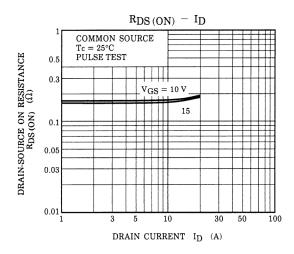


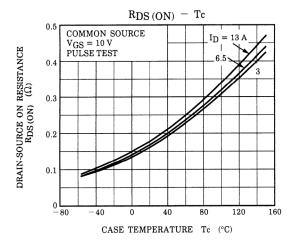


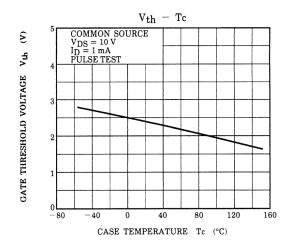


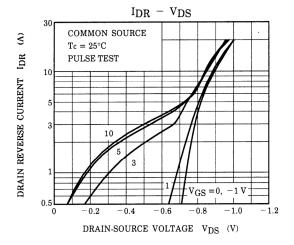


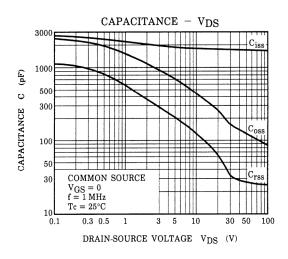


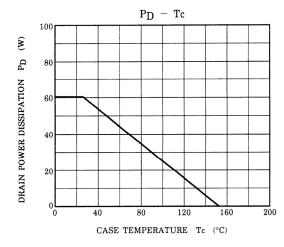


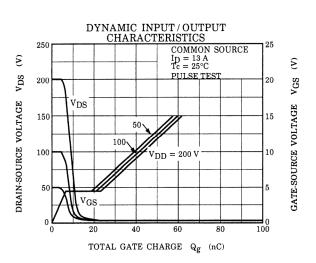




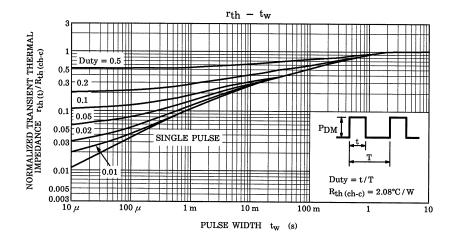


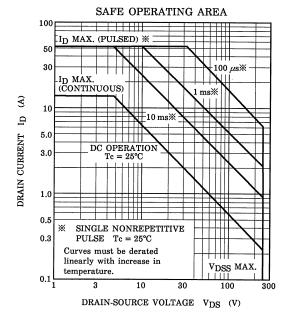


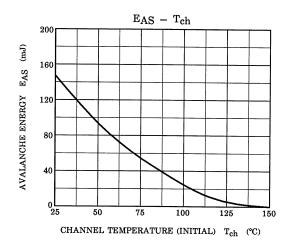


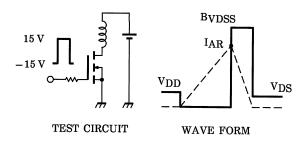


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$$R_{G} = 25 \Omega$$
  
 $V_{DD} = 50 \text{ V}, L = 1.48 \text{ mH}$   $EAS = \frac{1}{2} \cdot L \cdot R$ 

$$EAS = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left( \frac{BVDSS}{BVDSS - VDD} \right)$$

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